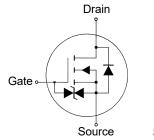
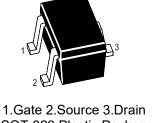
### **N-Channel Enhancement Mode MOSFET**

#### **Features**

- Built-in G-S Protection Diode
- Typical ESD Protection HBM Class 1C

Classification	Voltage Range(V)		
0A	< 125		
0B	125 to < 250		
1A	250 to < 500		
1B	500 to < 1000		
1C	1000 to < 2000		
2	2000 to < 4000		
3A	4000 to < 8000		
3B	≥ 8000		





SOT-323 Plastic Package

# **Applications**

- Portable appliances
- Battery management
- · High speed switch
- Low power DC to DC Converter

## Absolute Maximum Ratings(at Ta = 25°C unless otherwise specified)

Parameter	Symbol	Value	Unit
Drain-Source Voltage	V <sub>DS</sub>	60	V
Gate-Source Voltage	V <sub>GS</sub>	± 20	V
Continuous Drain Current	I <sub>D</sub>	2	Α
Peak Drain Current , Pulsed 1)	I <sub>DM</sub>	8	Α
Total Power Dissipation 2)	P <sub>tot</sub>	500	mW
Operating Junction and Storage Temperature Range	T <sub>J</sub> , T <sub>stg</sub>	- 55 to + 150	℃

#### **Thermal Characteristics**

Parameter	Symbol	Max.	Unit
Thermal Resistance from Junction to Ambient 2)	Reja	250	°C/W

 $<sup>^{1)}</sup>$  Pulse Test: Pulse Width ≤ 100 μs, Duty Cycle ≤ 2%,Repetitive rating, pulse width limited by junction temperature T<sub>J(MAX)</sub>=150°C.



<sup>&</sup>lt;sup>2)</sup> Device mounted on FR-4 substrate PC board, 2oz copper, with 1-inch square copper plate in still air.

# **MKB06N192LK**

# Characteristics at Ta = 25°C unless otherwise specified

Parameter	Symbol	Min.	Тур.	Max.	Unit
STATIC PARAMETERS	•				
Drain-Source Breakdown Voltage at I <sub>D</sub> = 250 μA	V <sub>(BR)DSS</sub>	60	-	-	V
Zero Gate Voltage Drain Current at V <sub>DS</sub> = 48 V	I <sub>DSS</sub>	ı	ı	1	μΑ
Gate-Source Leakage at $V_{GS} = \pm 16 \text{ V}$	I <sub>GSS</sub>	-	-	± 10	μΑ
Gate-Source Threshold Voltage at $V_{DS}$ = $V_{GS}$ , $I_D$ = 250 $\mu A$	V <sub>GS(th)</sub>	1	-	2.5	V
Drain-Source On-State Resistance at $V_{GS}$ = 10 V, $I_D$ = 1 A at $V_{GS}$ = 4.5 V, $I_D$ = 0.5 A	R <sub>DS(on)</sub>	- -	- -	137 192	mΩ
DYNAMIC PARAMETERS					
Forward Transconductance at $V_{DS} = 5 \text{ V}$ , $I_D = 1 \text{ A}$	<b>g</b> fs	-	4.8	-	S
Gate Resistance at $V_{GS} = 0 \text{ V}$ , $V_{DS} = 0 \text{ V}$ , $f = 1 \text{ MHz}$	R <sub>g</sub>	-	5.7	-	Ω
Input Capacitance at V <sub>GS</sub> = 0 V, V <sub>DS</sub> = 30 V, f = 1 MHz	C <sub>iss</sub>	-	310	-	pF
Output Capacitance at $V_{GS} = 0 \text{ V}$ , $V_{DS} = 30 \text{ V}$ , $f = 1 \text{ MHz}$	Coss	-	23.8	-	pF
Reverse Transfer Capacitance at $V_{GS} = 0 \text{ V}$ , $V_{DS} = 30 \text{ V}$ , $f = 1 \text{ MHz}$	C <sub>rss</sub>	-	18	-	pF
Total Gate Charge at $V_{DS}$ = 30 V, $V_{GS}$ = 10 V, $I_D$ = 1 A at $V_{DS}$ = 30 V, $V_{GS}$ = 4.5 V, $I_D$ = 1 A	Qg	-	6.8 3.3	- -	nC
Gate to Source Charge at $V_{DS}$ = 30 V, $V_{GS}$ = 10 V, $I_D$ = 1 A	Q <sub>gs</sub>	-	1.3	-	nC
Gate to Drain Charge at $V_{DS}$ = 30 V, $V_{GS}$ = 10 V, $I_D$ = 1 A	$Q_{gd}$	ı	1	-	nC
Turn-On Delay Time at $V_{DS}$ = 30 V, $V_{GS}$ = 10 V, $I_D$ = 1 A, $R_g$ = 3.9 $\Omega$	$t_{\text{d(on)}}$	ı	5	-	ns
Turn-On Rise Time at $V_{DS}$ = 30 V, $V_{GS}$ = 10 V, $I_D$ = 1 A, $R_g$ = 3.9 $\Omega$	<b>t</b> r	-	2	-	ns
Turn-Off Delay Time at $V_{DS}$ = 30 V, $V_{GS}$ = 10 V, $I_D$ = 1 A, $R_g$ = 3.9 $\Omega$	$t_{\text{d(off)}}$	-	7	-	ns
Turn-Off Fall Time at $V_{DS}$ = 30 V, $V_{GS}$ = 10 V, $I_D$ = 1 A, $R_g$ = 3.9 $\Omega$	t <sub>f</sub>	-	6	-	ns
Body-Diode PARAMETERS					
Drain-Source Diode Forward Voltage at Is = 1 A	V <sub>SD</sub>	-	-	1.2	V
Body Diodes Continuous Current	ls	-	-	2	Α
Body Diode Reverse Recovery Time at I <sub>S</sub> = 1 A, di/dt = 100 A / μs	t <sub>rr</sub>	-	7.8	-	ns
Body Diode Reverse Recovery Charge at $l_S = 1$ A, di/dt = 100 A / $\mu s$	Qrr	-	4	-	nC



#### **Electrical Characteristics Curves**

Fig. 1 Typical Output Characteristics

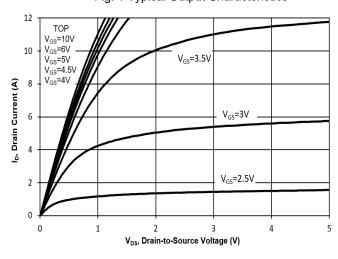


Fig. 2 Typical Transfer Characteristics

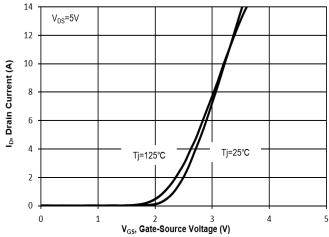


Fig. 3 On-Resistance vs. Drain Current

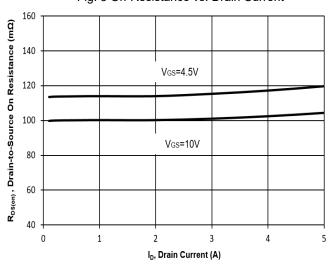


Fig. 4 On-Resistance vs. Gate-Source Voltage

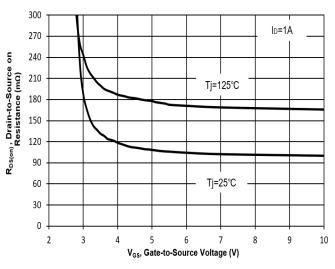


Fig. 5 On-Resistance vs.Ti

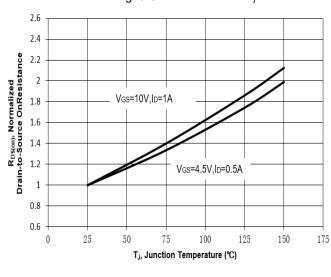
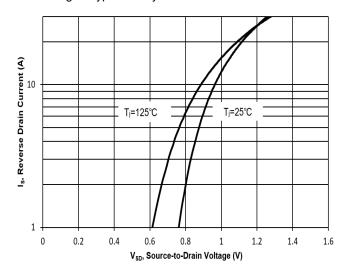


Fig. 6 Typical Body-Diode Forward Characteristics





#### **Electrical Characteristics Curves**

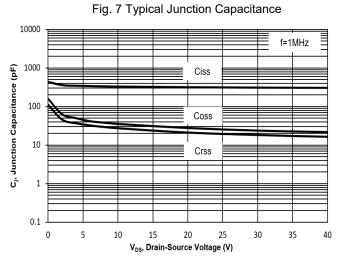


Fig. 8 Drain-Source Leakage Current vs. Ti

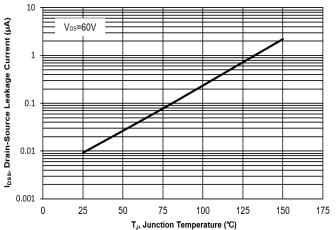


Fig. 9  $V_{(BR)DSS}$  vs. Junction Temperature

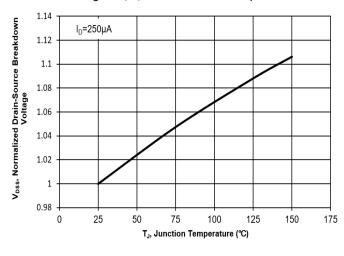


Fig. 10 Gate Threshold Variation vs. T<sub>j</sub>

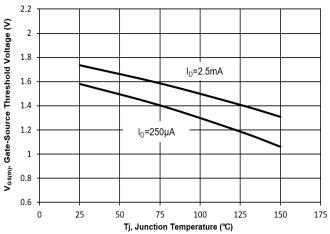
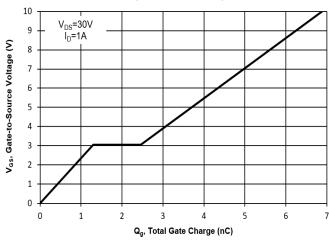


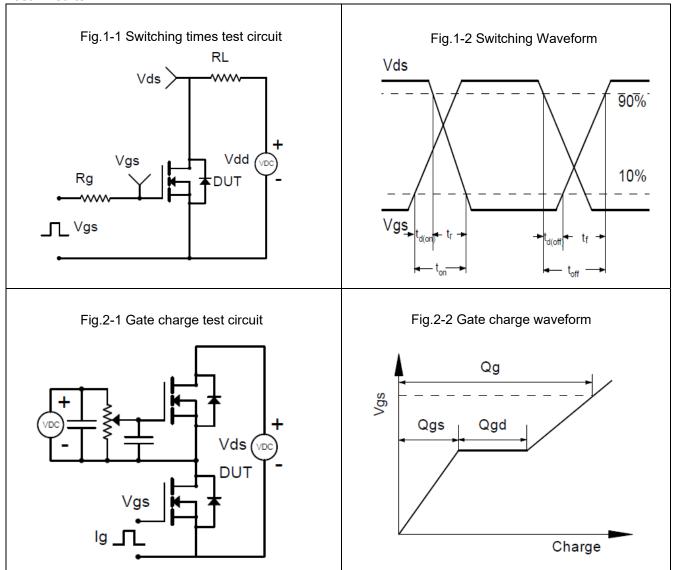
Fig. 11 Gate Charge





# **MKB06N192LK**

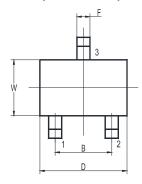
### **Test Circuits**

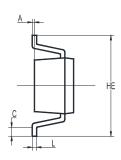


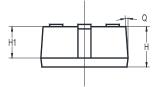


# Package Outline Dimensions (Units: mm)

**SOT-323** 

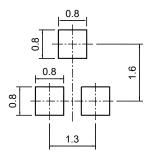






UNIT	Α	В	C	D	Н	H1	HE	F	Ш	W	Q
nana	0.1	1.4	0.2	2.1	1.0	0.7	2.4	0.35	0.15	1.35	5°
mm	MAX.	1.2	MIN.	1.9	0.8	TYP.	2.0	0.25	0.05	1.15	MAX.

### **Recommended Soldering Footprint**



# **Packing information**

Deeler	Tape Width	Pitch		Reel	Size	D D ID II 0 II
Package	(mm)	mm	inch	mm	inch	Per Reel Packing Quantity
SOT-323	8	4 ± 0.1	0.157 ± 0.004	178	7	3,000

### **Marking information**

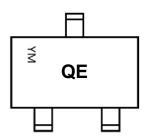
" QE " = Part No.

" YM " = Date Code Marking

" Y " = Year

" M " = Month

Font type: Arial



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